

HD74HC165

Parallel-load 8-bit Shift Register

REJ03D0581-0300 Rev.3.00 Jan 31, 2006

Description

This 8-bit serial shift register shifts data from Q_A to Q_H when clocked. Parallel inputs to each stage are enabled by a low level at the Shift/Load input. Also included is a gated clock input and a complementary output from the eighth bit.

Clocking is accomplished through a 2-input NOR gate permitting one input to be used as a clock inhibit function. Holding either of the clock inputs high inhibits clocking, and holding either clock input low with the Shift/Load input high enables the other clock input. Data transfer occurs on the positive going edge of the clock. Parallel loading is inhibited as long as the Shift/Load input is high. When taken low, data at the parallel inputs is loaded directly into the register independent of the state of the clock.

Features

• High Speed Operation: t_{pd} (Clock to Q_H) = 21 ns typ (C_L = 50 pF)

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$

• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC165P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	Р	_
HD74HC165FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Function Table

				Parallel	Internal	Output	
Shift/Load	Clock Inhibit	Clock	Serial	A H	Q_A	Q _B	Q _H
L	Х	Х	Х	ah	а	b	h
Н	L	L	Х	Х	Q_{A0}	Q_{B0}	Q _{H0}
Н	L		Н	Х	Н	Q_{An}	Q_{Gn}
Н	L		L	Х	L	Q_{An}	Q_{Gn}
Н	Н	Х	Х	Х	Q_{A0}	Q_{B0}	Q _{H0}

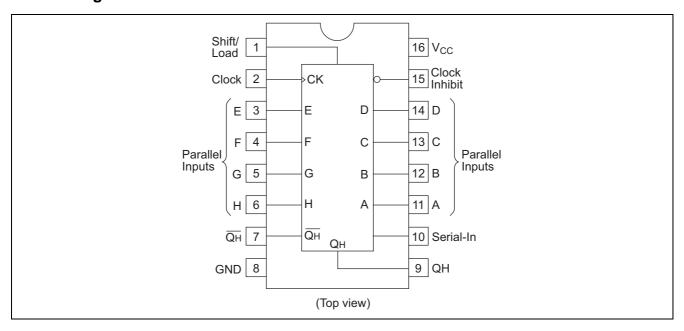
 Q_{Ao} to Q_{Ho} = Outputs remain unchanged.

 Q_{An} to Q_{Gn} = Data shifted from the previous stage on a positive edge at the clock input.

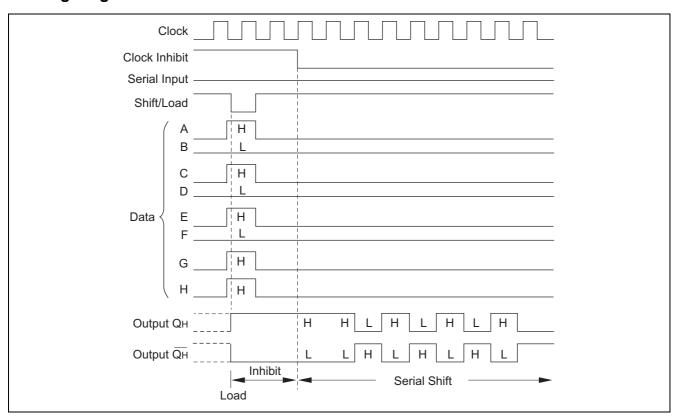
H: High levelL: Low levelX: Irrelevant



Pin Arrangement



Timing Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V _{CC}	-0.5 to 7.0	V
Input / Output voltage	Vin, Vout	-0.5 to V _{CC} +0.5	V
Input / Output diode current	I _{IK} , I _{OK}	±20	mA
Output current	I ₀	±25	mA
V _{CC} , GND current	I _{CC} or I _{GND}	±50	mA
Power dissipation	P _T	500	mW
Storage temperature	Tstg	-65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V _{CC}	2 to 6	V	
Input / Output voltage	V _{IN} , V _{OUT}	0 to V _{CC}	V	
Operating temperature	Та	-40 to 85	°C	
		0 to 1000		V _{CC} = 2.0 V
Input rise / fall time ^{*1}	t _r , t _f	0 to 500	ns	V _{CC} = 4.5 V
		0 to 400		$V_{CC} = 6.0 \text{ V}$

Note: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

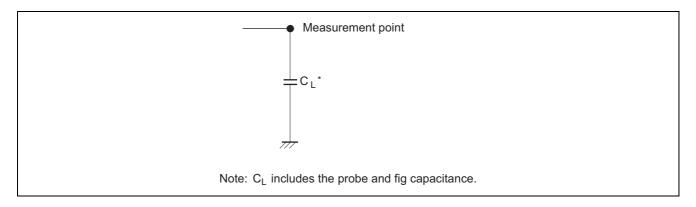
			Т	a = 25°	С	Ta = -40	to+85°C		
Item	Symbol	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Input voltage	V_{IH}	2.0	1.5	_	_	1.5	_	V	
		4.5	3.15	_	_	3.15	_		
		6.0	4.2	-	_	4.2			
	V_{IL}	2.0		_	0.5	_	0.5	V	
		4.5		_	1.35	_	1.35		
		6.0	_	_	1.8	_	1.8		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9		V	Vin = V_{IH} or V_{IL} $I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4	_		
		6.0	5.9	6.0	_	5.9	_		
		4.5	4.18	_	_	4.13	_		$I_{OH} = -4 \text{ mA}$
		6.0	5.68	_	_	5.63	_		$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} \text{ or } V_{IL} \mid I_{OL} = 20 \mu A$
		4.5	-	0.0	0.1	_	0.1		
		6.0	_	0.0	0.1	_	0.1		
		4.5	_	_	0.26	_	0.33		$I_{OL} = 4 \text{ mA}$
		6.0	_	_	0.26	_	0.33		$I_{OL} = 5.2 \text{ mA}$
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GND
Quiescent supply current	I _{CC}	6.0	_	_	4.0	_	40	μΑ	Vin = V_{CC} or GND, lout = $0 \mu A$

Switching Characteristics

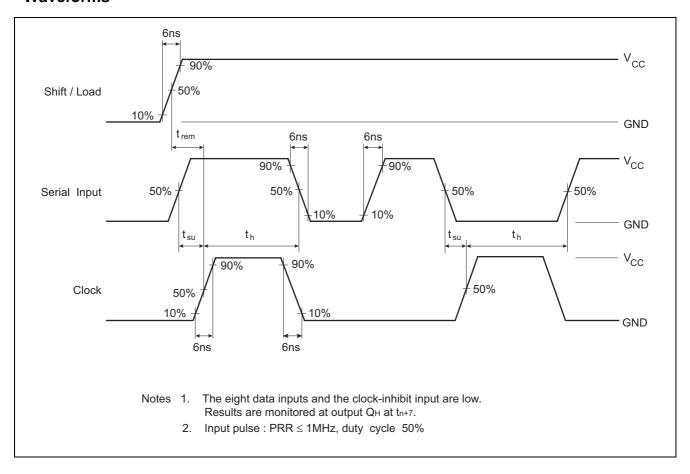
 $(C_L = 50 \text{ pF}, \text{Input } t_r = t_f = 6 \text{ ns})$

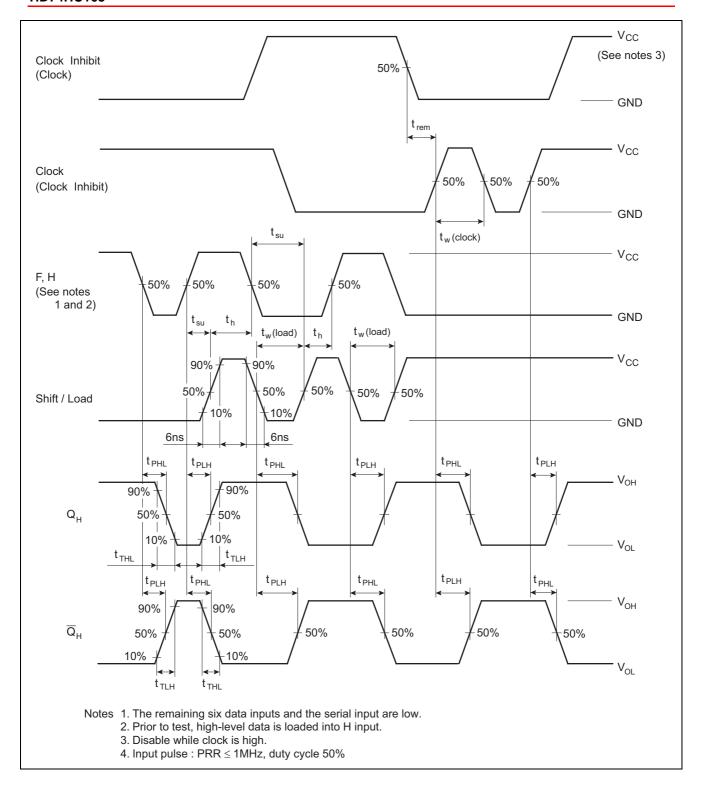
			Т	a = 25°	С	Ta = -40 to +85°C			
Item	Symbol	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	f _{max}	2.0	_	_	5	_	4	MHz	
frequency		4.5	_	_	27	_	21		
		6.0	_	_	32	_	25		
Propagation delay	t _{PLH} , t _{PHL}	2.0	_	_	150	_	190	ns	Clock to Q _H or Q _H
time		4.5	_	21	30	_	38		
		6.0	_	_	26	_	33		
		2.0	_	_	160	_	200	ns	Shift/Load to Q _H or $\overline{\mathbb{Q}}_{H}$
		4.5	_	23	32	_	40		
		6.0	_	_	27	_	34		
		2.0	_	_	150	_	190	ns	H to Q _H or $\overline{\mathbf{Q}}_{H}$
		4.5	_	21	30	_	38		
		6.0	_	_	26	_	33		
Setup time	t _{su}	2.0	100	_	_	125	_	ns	Parallel data inputs to
		4.5	20	-3	_	25	_		Shift/Load
		6.0	17	_	_	21	_		
		2.0	100	_	_	125	_	ns	Serial input to Clock
		4.5	20	3	_	25	_		
		6.0	17	_	_	21	_		
		2.0	100	_	_	125	_	ns	Shift/load to Clock
		4.5	20	_	_	25	_		
		6.0	17		_	21	_		
Removal time	t _{rem}	2.0	100	_	_	125		ns	Clock to Clock inhibit or
		4.5	20	6		25			Clock inhibit to Clock
		6.0	17	_	_	21	_		
Hold time	t _h	2.0	5	_		5		ns	Shift/Load to parallel data
		4.5	5	-3		5			input
		6.0	5	_		5			
		2.0	5	_		5		ns	Clock to Serial input
		4.5	5	3	_	5	_		
		6.0	5		_	5			
		2.0	5	_	_	5	_	ns	Clock to Shift/Load
		4.5	5	_	_	5	_		
		6.0	5	_	_	5	_		
Pulse width	t _w	2.0	80	_	_	100	_	ns	Clock, Shift/Load
		4.5	16	6	_	20	_		
		6.0	14	_		17	_		
Output rise/fall	t_{TLH} , t_{THL}	2.0	_	_	75	_	95	ns	
time		4.5	_	5	15	_	19		
		6.0	_	_	13	_	16		
Input capacitance	Cin	_	_	5	10	_	10	pF	

Test Circuit

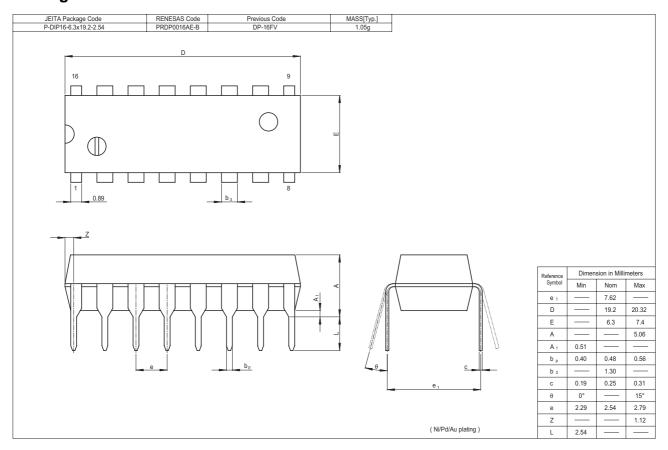


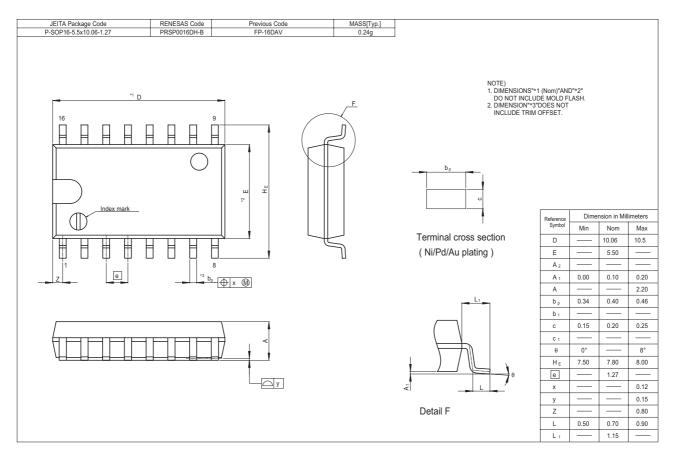
Waveforms





Package Dimensions





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